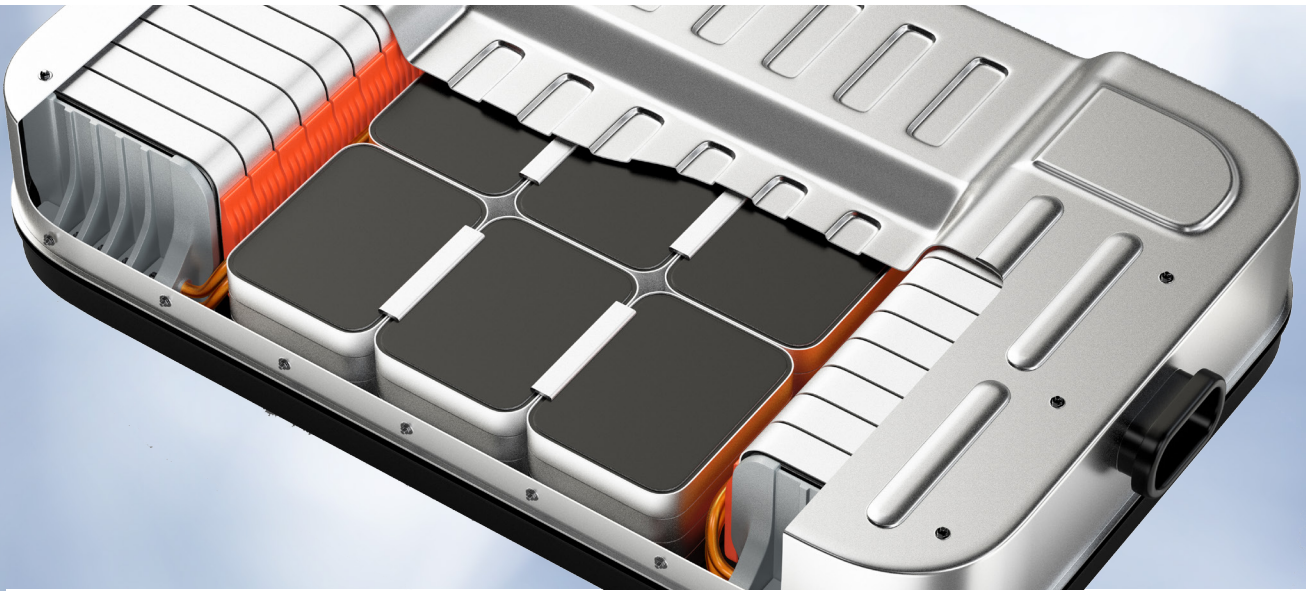


Gap Filler

Your Customized Solution for Conducting Heat Away from Your Components



RAKU® SIL 27-1004

A soft, thermally conductive, form-in-place elastomer used as a gap filler. It is a highly viscous, paste, two-component silicone elastomer. The curing takes place at room temperature or in the heat.



Benefits

- Very good thermal conductivity
- Quick reaction at room temperature
- Fast cure with exposure to heat
- Low shore hardness
- Good electrical values
- Useful temperature range - 60 to 200°C



Applications

- Power electronics
- Automotive Electronic Components
- Computers and peripherals.
- Application between heat generating semiconductor devices and heat sinks

Features

RAKU® SIL 27-1004

Color	light grey
Viscosity A [mPa*s]	100,000
Viscosity B [mPa*s]	180,000
Density A-Component [g/ml]	2.5
Density B-Component [g/ml]	2.4
Mixing Ratio A : B [per weight]	100 : 100
Pot Life 20 °C [min]	35
Density [g/ml]	2.5
Hardness [Shore]	20 Shore A
Operating Temp [°C]	-60 bis +200 °C
Thermal Conductivity [W/(m*K)]	1.70
Dielectric Strength [kV/mm]	20

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